

Gate resistor installed Dual N-channel MOSFET

KFC4B22180L Datasheet

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1. GENERAL DESCRIPTION

Gate resistor installed Dual N-channel MOSFET For lithium-ion secondary battery protection circuits

2. FEATURES

- Low source-source ON Resistance: RSS (on) typ. = 9.4 m Ω (VGS = 4.5 V)
- CSP (Chip Size Package)
- RoHS compliant (EU RoHS / MSL: Level 1)

3. MARKING SYMBOL: 17

4. PACKAGING

Embossed type (Thermo-compression sealing): 10,000 pcs / reel (standard)

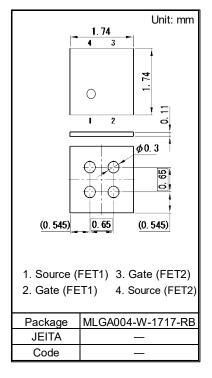
5. ABSOLUTE MAXIMUM RATINGS Ta = 25 °C

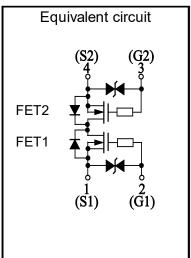
| Parameter | Symbol | Rating | Unit | | |
|---------------------------|--------|--------|-------------|----|--|
| Source-source Voltage | | VSS | 20 | V | |
| Gate-source Voltage | | VGS | ±8 | V | |
| Source Current | DC | IS1 *1 | 5 | А | |
| | | IS2*2 | 10 | | |
| | Pulsed | ISp*3 | 50 | | |
| Total Power Dissipation | DC | PD1 *1 | 0.4 | W | |
| | | PD2 *2 | 1.5 | | |
| Channel Temperature | | Tch | 150 | °C | |
| Storage Temperature Range | | Tstg | -55 to +150 | °C | |

6. THERMAL CHARACTERISTICS Ta = 25 °C

| Parameter | Symbol | Rating | Unit |
|-----------------------------|---------|--------|----------|
| The word Decistores (sh. s) | Rth1 *1 | 312 | °C / \\/ |
| Thermal Resistance (ch-a) | Rth2*2 | 83 | °C/W |

- Note *1 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm) using the minimum recommended pad size (36μm Copper).
 - 2 Mounted on ceramic substrate (70 mm x 70 mm x t1.0 mm).
 - *3 $t = 10 \mu s$, Duty Cycle $\leq 1 \%$





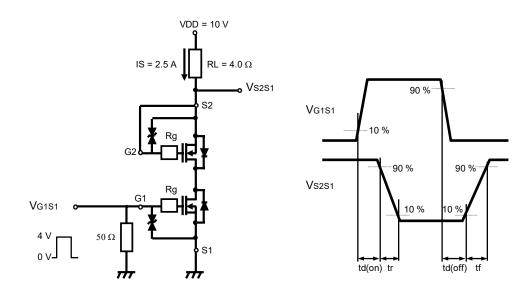


7. ELECTRICAL CHARACTERISTICS Ta = 25 °C ± 3 °C

| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|-----------------------------------|----------|----------------------------------|------|------|-------|------|
| Source-source Breakdown Voltage | VSSS | IS = 1 mA, VGS = 0 V | 20 | | | V |
| Zero Gate Voltage Source Current | ISSS | VSS = 20 V, VGS = 0 V | | | 1.0 | μΑ |
| Gate-source Leakage Current | IGSS1 | VGS = ±8 V, VSS = 0 V | | | ±10.0 | μА |
| | IGSS2 | VGS = ±5 V, VSS = 0 V | | | ±1.0 | |
| Gate-source Threshold Voltage | Vth | IS = 0.64 mA, VSS = 10 V | 0.35 | 0.90 | 1.40 | V |
| Source-source On-state Resistance | RSS(on)1 | IS = 2.5 A, VGS = 4.5 V | 7.0 | 9.4 | 11.9 | mΩ |
| | RSS(on)2 | IS = 2.5 A, VGS = 3.8 V | 7.3 | 10.0 | 12.9 | |
| | RSS(on)3 | IS = 2.5 A, VGS = 3.1 V | 8.1 | 11.1 | 15.8 | |
| | RSS(on)4 | IS = 2.5 A, VGS = 2.5 V | 8.6 | 13.4 | 22.6 | |
| Body Diode Forward Voltage | VF(s-s) | IF = 2.5 A, VGS = 0 V | | 0.8 | 1.2 | V |
| Input Capacitance *1 | Ciss | | | 2440 | | |
| Output Capacitance *1 | Coss | VSS = 10 V, VGS = 0 V, f = 1 kHz | | 200 | | pF |
| Reverse Transfer Capacitance *1 | Crss | | | 160 | | |
| Turn-on Delay Time *1,*2 | td(on) | VDD = 10 V, VGS = 0 to 4 V | | 0.9 | | |
| Rise Time *1,*2 | tr | IS = 2.5 A | | 1.6 | | μS |
| Turn-off Delay Time *1,*2 | td(off) | VDD = 10 V, VGS = 4 to 0 V | | 5.0 | | |
| Fall Time *1,*2 | tf | | | 2.4 | | μS |
| Total Gate Charge *1 | Qg | VDD = 10 V | | 23 | | |
| Gate-source Charge *1 | Qgs | VGS = 0 to 4 V | | 6 | | nC |
| Gate-drain Charge *1 | Qgd | IS = 2.5 A | | 5 | | |

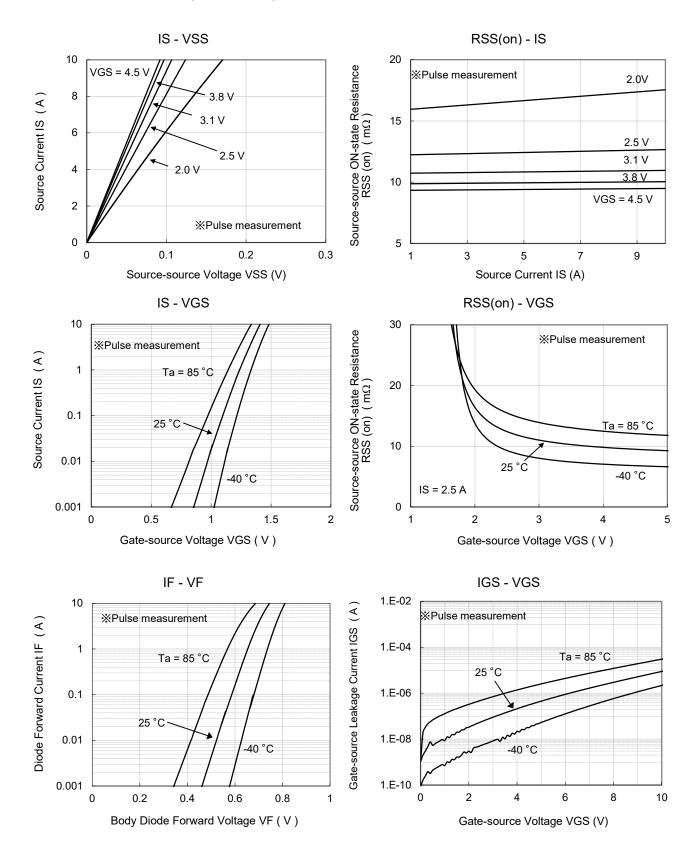
Note Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

 ^{*1} Guaranteed by design, not subject to production testing
 *2 Measurement circuit for Turn-on Delay Time / Rise Time / Turn-off Delay Time / Fall Time



8. TECHNICAL DATA (Reference)

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TECHNICAL DATA (Reference)

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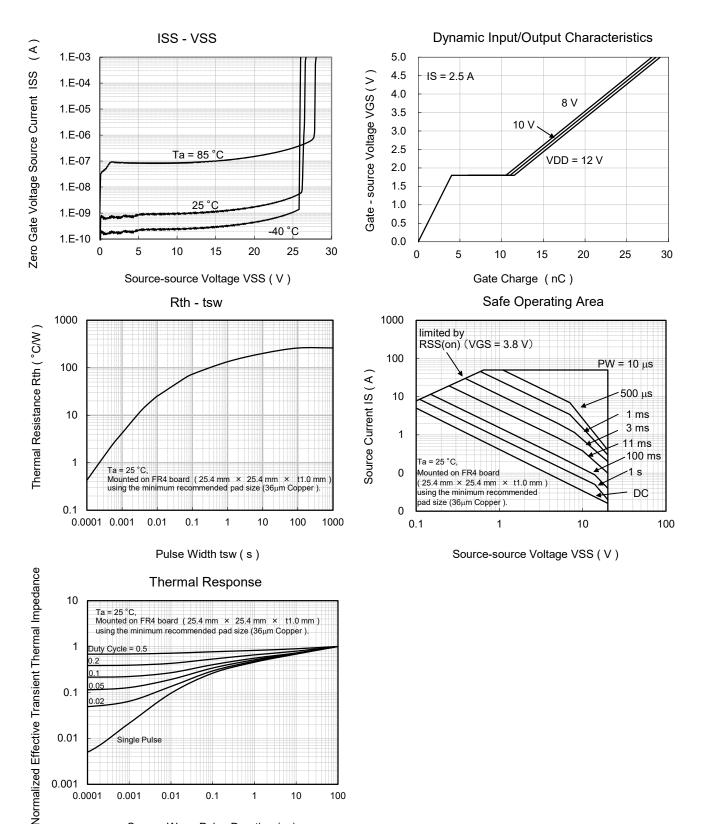
0.01

0.0001

0.001

0.01

Square Wave Pulse Duration (s)

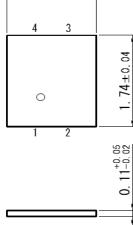


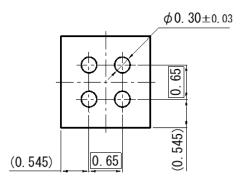
100

Unit: mm

9. OUTLINE

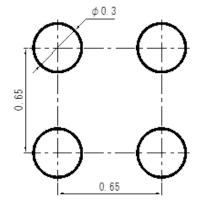
1.74±0.04 4 3





10. LAND PATTERN (Reference)

Unit: mm



Important notice:

Solder Mask Defined (SMD) pattern is strongly recommended for pad design. Please check the information in the Nuvoton WL-CSP Application Notes about mounting process.



11. REVISION HISTORY

| Date | Revision | Description |
|------------|----------|---|
| 2021.2.3 | 1.00 | 1. Initially issued. |
| 2021.7.26 | 1.01 | Revised Safe Operating Area in page 5. |
| 2021.08.31 | | Changed document name from Product Standards to Datasheet. |
| | 1.02 | 2. Added important notice in Land Pattern. |
| | | 3. Added special attention and precautions notes. |

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